

Toshiba TPC8402 Handbook

Field effect transistor silicon n, p channel mos type (n-mosvi/u-mosii)

Bookmarks

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TOSHIBA Field Effect Transister Silicon Ν, Ρ Channel MOS Type (π–MOSVI/U–MOSII) Lithium-Ion Secondary Battery Applications

Notebook PCs

Portable Equipment Applications Low drain-source ON resistance : P Channel R High forward transfer admittance : P Channel |Y Low leakage current : P Channel I N Channel I Enhancement-mode : P Channel V = -0.8~ -2.0 V (V th N Channel V = 0.8~2.0 V (V th

Absolute Marios Ration

Characteristics —									
Drain-source voltage	2								
Drain-gate voltage (I	R								
GS	IX.								
Gate-source voltage									
DC									
Drain current									
Pulse									
Single-device operat	ion								
Drain power								1	
dissipation									
(t = 10s)									
Single-device value at									Å
(Note 2a)									
dual operation (Note 3	Bb)								
Single-device operat	ion								6
Drain power									14
dissipation									
(t = 10s)									0.595TYP
Single-device value at									
(Note 2b)									1225
dual operation (Note 3	Bb)								1
Single-pulse avalance	he energy								-
Avalanche current									
Repetitive avalanche	e energy								1
Single-device value at	operation								240
(Note 2a, Note 3b, Not	te 5)								17.
Channel temperatur	Ê						8	6	~
Storage temperature	range					· · · · · ·	8		1
Note: For Notes 1 to	5, see the next	page.							ŝ
Using continuously	under heavy l	oads (e.g. the appl	ication	of hiah t	emperature	/current/volt	age and	the	
significant change	n temperature	etc.) may cause t	this prod	duct to d	lecrease in t	the reliabilit	v signific	antly e	ven -
if the operating cor	ditions (i e or	erating temperatu	re/curre			within the	ahsol u te	maxim	um
rating co		cruting temperata	re/curic		ge, etc., are		absolute	maxin	um
ratings.	13. 								
Please design the a	ippropriate rel	ability upon review	ving the	Toshiba	Semicondu	ictor Reliabi	ity Hand	book	
("Handling Precaut	ons"/Derating	Concept and Meth	ods) an	d individ	ual reliabilit	y data (i.e.	reliability	test re	port
and estimated failu	re rate, etc).		-			2	8	5	
This transistor is ar	electrostatic-	sensitive device. H	andle w	ith care					
	5 3						8	8	
TDCO	コン								
IFLO	HUZ								
DS (ON)									
N Channel R	8		-						
DS (ON)									-
= 7 S (typ.)									
fs								Î	
N Channel IY									8
I = 6.5 (typ)	di		-					8	
f = 0.5 (typ.)							~		
10								Ĩ	1
$= -10 \mu A (V)$									
D22									
DS	10							8	
= 10 µA (V							8	5	
DSS									
DS			<u></u>	,	-			£.	

= -10 V, I	roeuira	
= −1mA)	USHIDA	
DS D		
= 10 V I		
$= 1m\Delta$		
DS		
D		
$(T_{2} = 25^{\circ}C)$		
Rating		
Symbol		
P Channel N Channe	el	
V		
-30		8
DSS		L P
V		
-30		
DGR		间
v +20		1000
±20 GSS		0.595TYP
(Note 1)		
		H
-4.5		
D		
(Note 1)		析
10		Ч <u>а</u> ,
-10		12
P		2
1.5		1
D (1)		3
(Note 3a)		
P		C T T
1.0		
P		
0.75		
D (1)		
(Note 3a)		
P 0.45		
D (2)		
26.3		
E		
AS		
(Note 4a)		
1		E C
-4.5 AR		
E		
0.10		5.9
AR		
Т		
150		2000
cn T		
-55~150		
stg		
= 27 mΩ (typ.)		



Next Page

Related Manuals for Toshiba TPC8402

Semiconductors Toshiba Semiconductor Handling Manual

Toshiba semiconductor handling guide (24 pages)

Summary of Contents for Toshiba TPC8402

<u>Page 1</u> (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Page 2: Thermal Characteristics

TPC8402 Thermal Characteristics Characteristics Symbol Max. Unit Single-device operation 83.3 th (ch-a) (1) (Note 3a) Thermal resistance, channel to ambient (t = 10s) (Note 2a) Single-device value at dual operation th (ch-a) (2) (Note 3b) $^{\circ}$ C/W Single-device operation th (ch-a) (1)

Page 3: Electrical Characteristics

TPC8402 P-ch Electrical Characteristics (Ta = 25°C) Characteristics Symbol Test Condition Min. Typ. Max. Unit Gate leakage current = ± 16 V, V = 0 V — $-\pm 10$ µA Drain cut-off current = -30 V, V = 0 V —...

<u>Page 4</u> TPC8402 N-ch Electrical Characteristics (Ta = 25°C) Characteristics Symbol Test Condition Min. Typ. Max. Unit Gate leakage current = ± 16 V, V = 0 V — $-\pm 10$ µA Drain cut-off current = 30 V, V = 0 V —...

<u>Page 5</u> TPC8402 P-ch - I DS (ON) V GS = -4 V V GS = -10 V Common source Ta = 25°C Pulse test -0.1 - 0.3 - 1 - 3 - 10 - 30 - 100 Drain current I 2006-11-13...

Page 6 TPC8402 P-ch - Ta DS (ON) Common source Pulse test I D = -4.5 A - 2.2 A - 1.3 A I D= -4.5 A, -2.2 A V GS = -4 V -1.3 A -10 V -80 -40 Ambient temperature Ta (°...

Page 7: Single Pulse

TPC8402 P-ch - t 1000 DEVICE MOUNTED ON A GLASS-EPOXY BOARD (a) (NOTE 2a) (1) SINGLE-DEVICE OPERATION (NOTE 3a) (2) SINGLE-DEVICE VALUE AT DUAL OPERATION (NOTE 3b) DEVICE MOUNTED ON A GLASS-EPOXY BOARD (b) (NOTE 2b) (3) SINGLE-DEVICE OPERATION (NOTE 3a)

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Page 9 TPC8402 N-ch - Ta DEVICE MOUNTED ON A GLASS-EPOXY BOARD (a) (NOTE 2a) (1) SINGLE-DEVICE OPERATION (NOTE 3a) (2) SINGLE-DEVICE VALUE AT DUAL OPERATION (NOTE 3b) DEVICE MOUNTED ON A GLASS-EPOXY BOARD (b) (NOTE 2b) (3) SINGLE-DEVICE OPERATION (NOTE 3a)

Page 10 TPC8402 N-ch – t 1000 DEVICE MOUNTED ON A GLASS-EPOXY BOARD (a) (NOTE 2a) (1) SINGLE-DEVICE OPERATION (NOTE 3a) (2) SINGLE-DEVICE VALUE AT DUAL OPERATION (NOTE 3b) DEVICE MOUNTED ON A GLASS-EPOXY BOARD (b) (NOTE 2b) (3) SINGLE-DEVICE OPERATION (NOTE 3a)

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